



Better Bond TC-20™ Instructions

Always test this adhesive on scrap material to determine its suitability for the project at hand.

Sealers or coatings on the substrate will prevent the adhesive from adequate bonding. TC-20™ will only bond to a porous substrate. Remove any surface contaminants and test for porosity by placing a drop of water on the substrate. The surface can be considered porous if the water drop absorbs within 15 seconds. Some substrates can be made more porous by scuff sanding with 60 or 80 grit sandpaper. The minimum use temperature for the TC-20 adhesive is 65°F.

Gently scuff-sand the back of the copper veneer with 80 or 120 grit sandpaper. In a well-ventilated area, thoroughly wash the back side of the copper with water or acetone using a steel wool or synthetic steel wool pad. Apply the adhesive to the substrate with a glue roller. A thin coat of glue is generally sufficient. Set the copper veneer onto the substrate while the adhesive is still wet.

Clamp the surface for 45 minutes using a flat piece of plywood and plenty of weight on top. A vacuum press will also work very nicely. Allow 90 minutes of curing before machining. Full bond strength takes place after 24 hours.

Not suitable for exterior projects, even if protected from sun/rain. Not for use with copper containing zinc or copper surfaces which have been treated with a protective or gloss-enhancing chemical or process.

Please Note: Avoid gross contact with skin. Wear appropriate eye and skin protection. Read the Safety Data Sheet before use. Our only obligation shall be to replace or pay for any material proven by us to be defective. We assume no liability for damages of any kind. User accepts the product "as is" and without warranty expressed or implied. The suitability of the product for an intended use shall be solely at the user's discretion. If the user does not accept these terms, the unopened product is to be returned immediately.